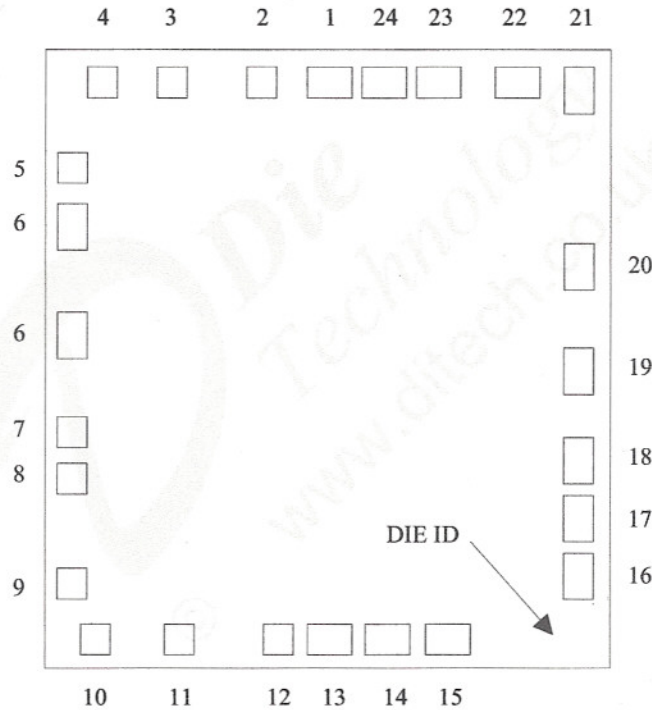




Sierra Components, Inc.

2222 Park Place Building 3 Suite E • Minden, Nevada 89423
 Phone: 775.783.4940 Fax: 775.783.4947



PAD FUNCTIONS

- 1 BHB
- 2 NOT BHI
- 3 BLI
- 4 ALI
- 5 NOT AHI
- 6 V_{SS} (both pads)
- 7 RDEL
- 8 UVLO
- 9 RFSH
- 10 DIS
- 11 CLI
- 12 NOT CHI
- 13 CHB
- 14 CHO
- 15 CHS
- 16 AHB
- 17 AHO
- 18 AHS
- 19 CLO
- 20 V_{DD}
- 21 ALO
- 22 BLO
- 23 BHS
- 24 BHO

The information given is believed to be correct at the time of issue.

Please verify your requirements prior to commencement of any assembly process, as no liability for omission or error can be accepted.

Chip back potential is the level at which bulk silicon is maintained either by bond pad connection or in some cases the potential to which the chip back must be connected if stated above.

Note: 1 mil = 0.001inch

<u>APPROVED</u> GB DATE: 17/09/2007	HIP4086A INTERSIL	<u>DIE INFORMATION</u> DIMENSIONS (Mils): 109 x 124 x 14 BOND PADS (Mils): 4 x 4 DIE ID: HIP4086 GEOMETRY: BACK POTENTIAL:
<u>SERIAL NUMBER</u> 008743		<u>METALLISATION</u> TOP: Al BACK: Si